

METHOD AND APPARATUS FOR HEAT SINK

ABSTRACT

An assembly for dissipating heat includes a die (102) containing an electronic circuit (a "chip") and a heat transfer element (104) ("HTE") proximate to the chip and tending to be thermally conductive. The HTE has a face (110) opposite the chip. The heat sink (112) has a face tending to match the HTE face (110). The heat sink (112) and HTE faces (110) are held proximate to one another. The heat sink face (112) and HTE face (110) entirely overlay the chip so that heat may dissipate in a direct line from the chip to the HTE (104) and the heat sink (112), and also outwardly therefrom.

Fig. 1